



TFW 1775

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q67726

Mitsuo OSADA, et al.

Appln. No.: 10/009,822

Group Art Unit: 1775

Confirmation No.: 6202

Examiner: Michael E. Lavilla

Filed: December 13, 2001

For: MATERIAL FOR A HEAT DISSIPATION SUBSTRATE FOR MOUNTING A SEMICONDUCTOR, METHOD OF PRODUCING THE SAME, AND CERAMIC PACKAGE USING THE SAME

AMENDMENT UNDER 37 C.F.R. § 1.111

MAIL STOP AMENDMENT

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated August 24, 2005, please amend the above-identified application as follows on the accompanying pages.

Amendment Under 37 CFR 1.111
U.S. Application No. 10/009,822

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

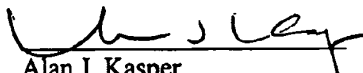
Respectfully submitted,

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WASHINGTON OFFICE

23373

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Date: November 23, 2005